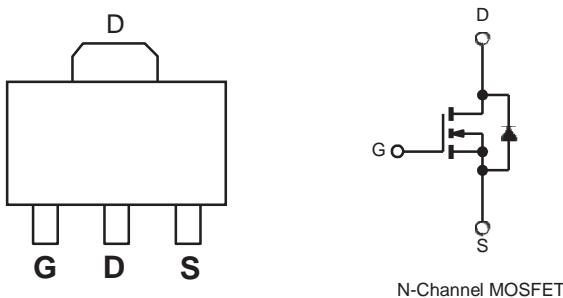




MOSFET PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A) ^a	Q _g (Typ.)
100	0.126 at V _{GS} = 10 V	3.1	2.9 nC
	0.134 at V _{GS} = 6 V	2.9	
	0.139 at V _{GS} = 4.5 V	2.6	

FEATURES

- TrenchFET® PowerMOSFET
- 100 % R_g and UIS Tested
- Material categorization:



APPLICATIONS

- DC/DC Converters / Boost Converters
- Load Switch
- LED Backlighting in LCD TVs
- Power Management for Mobile Computing

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)				
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Voltage		V _{GS}	± 20	
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	I _D	3.1	
	T _C = 70 °C		2.5	
	T _A = 25 °C		2.2 ^{b,c}	
	T _A = 70 °C		1.8 ^{b,c}	
Pulsed Drain Current (t = 300 µs)		I _{DM}	8	A
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	2.1	
	T _A = 25 °C		1b, c	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	3	
Single Pulse Avalanche Energy		E _{AS}	0.45	mJ
Maximum Power Dissipation	T _C = 25 °C	P _D	2.5	W
	T _C = 70 °C		1.6	
	T _A = 25 °C		1.25 ^{b, c}	
	T _A = 70 °C		0.8 ^{b, c}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Typical	Maximum
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	75	100
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	50

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 166 °C/W.